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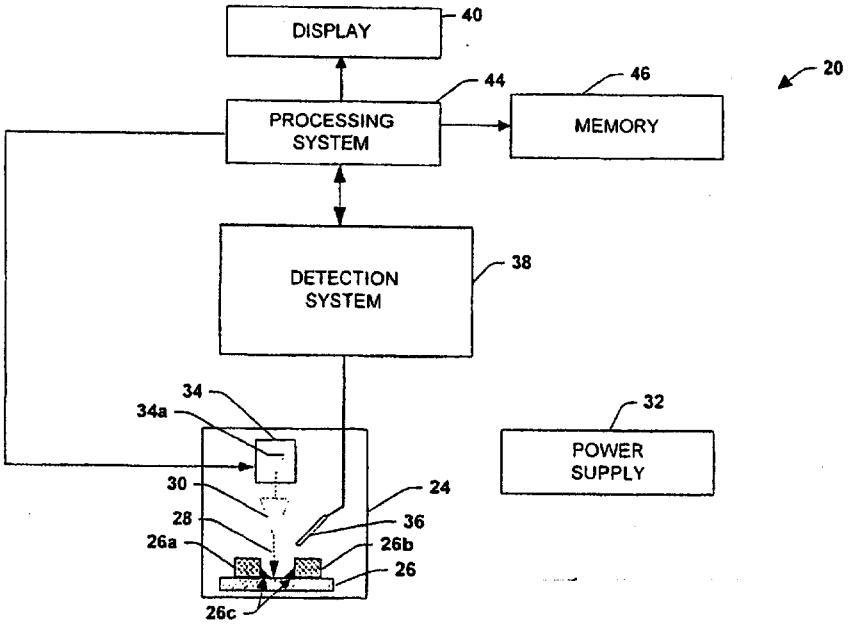
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(54) Title: ANALYSIS OF CD-SEM SIGNAL TO DETECT SCUMMED/CLOSED CONTACT HOLES AND LINES



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(57) Abstract: A system (20) is provided for detecting scumming in a wafer (26). The system (20) includes an analysis system (24) for providing a signal (18) corresponding to a surface portion of the wafer (26) and a processing system (44) operatively coupled to the analysis system (24). The processing system (44) is configured to determine a shape of at least a portion (18a, 18c) of the signal (18) and, the processing system (44) detects scumming in the wafer (26) based upon the shape of at least a portion (18a, 18c) of the signal (18).

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